

REMARKS/ARGUMENTS

Claims 1-20 are pending.

Claims 9-11, 13 were rejected under 35 U.S.C. § 112, 2nd Paragraph.

Claims 1, 5, 7, 9, 12, 14-17 were rejected under 35 U.S.C. § 102(e) for allegedly being anticipated by Skoll et al., U.S. Patent No. 6,684,379.

Claims 2-4, 18-20 were rejected under 35 U.S.C. § 103(a) for allegedly being unpatentable in view of Skoll et al. and Katzir et al., U.S. Patent Application Publication No. U.S. 2003/0006364.

Claims 6, 10, 13 were rejected under 35 U.S.C. § 103(a) for allegedly being unpatentable over Skoll et al..

Claims 8 and 11 were rejected under 35 U.S.C. § 103(a) for allegedly being unpatentable in view of Skoll et al. and Cabib et al., U.S. Patent No. 5,856,871.

The present invention is directed to semiconductor wafer inspections. An aspect of the present invention as recited in the pending claims includes obtaining information from an inspection or measurement of a portion of the wafer. The information is overlaid with an image of the portion of the wafer that was inspected or measured.

Skoll et al. is directed to a design workstation for analyzing integrated circuits. Skoll et al. show in Fig. 5 a navigation window (230) which displays an image of an IC. Mosaic-views (232, 234, 236 and 238) show results of a deconstruction operation performed on a slice (240) this is identified in the navigation window. Each mosaic-view (232, 234, 236 and 238) different construction details of the slice 240. *Col. 9, lines 19-42*. These mosaic-views (232, 234, 236 and 238) are not produced by an inspection or measurement of the slice (240). Skoll et al. do not teach overlaying an image with inspection or measurement information.

Figs. 4 and 5 of Skoll et al. further shows that the navigation window (230), which displays an image of an IC, and the mosaic-views (232, 234, 236 and 238) are displayed in a display area 228 of a visual display (222, Fig. 4). The mosaic-views do not overlay the image of the IC displayed in the navigation window. Skoll et al. therefore do not teach that the information is overlaid with an image of the wafer, as recited in the independent claims.

Katzir et al. describe an inspection system. Fig. 1B shows an imaging device 26 and a set of acquired images 240, 242, 244, 246, and 248 of a board 22. A defect analyzer 234 receives the image data and provides a defect report 236 reporting defects on board 22.

Paragraphs [0031]-[0032]. Katzir et al. do not disclose displaying an image of a region of the wafer by overlaying inspection or measurement information over the image of the region.

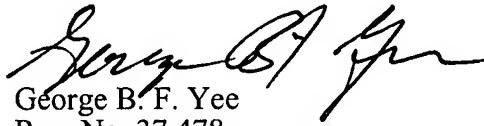
Cabib et al. disclose film thickness mapping. They describe how determine film thickness, but do not discuss or suggest displaying an image by overlapping film thickness information over an image of the object for which the thickness determination was made.

CONCLUSION

In view of the foregoing, all claims now pending in this Application are believed to be in condition for allowance. The issuance of a formal Notice of Allowance at an early date is respectfully requested.

If the Examiner believes a telephone conference would expedite prosecution of this application, please telephone the undersigned at 650-326-2400.

Respectfully submitted,


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